

THIS SHEET HAS BEEN
REPLACED

CANTILEVERED BALL CONNECTION FOR
INTEGRATED CIRCUIT CHIP PACKAGE

ABSTRACT OF THE DISCLOSURE

An electronic device includes an integrated circuit chip, an interposer and a printed circuit board. A first ball connector is used to connect the interposer to printed circuit board. The interposer may be connected to the integrated circuit chip by a second ball connector or a wire bond. The first ball connector is disposed on a cantilever structure formed in the interposer. The cantilever is formed by creating a channel in the interposer. The cantilever absorbs stress caused by a difference between the thermal expansion of the integrated circuit chip as compared to the printed circuit board. The cantilever thus reduces stress in the ball connector by allowing the ball connector to move within a plane defined by the interposer.

Figure 2

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